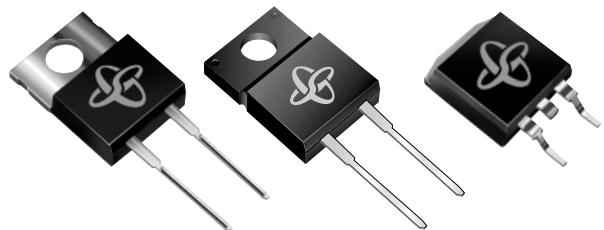
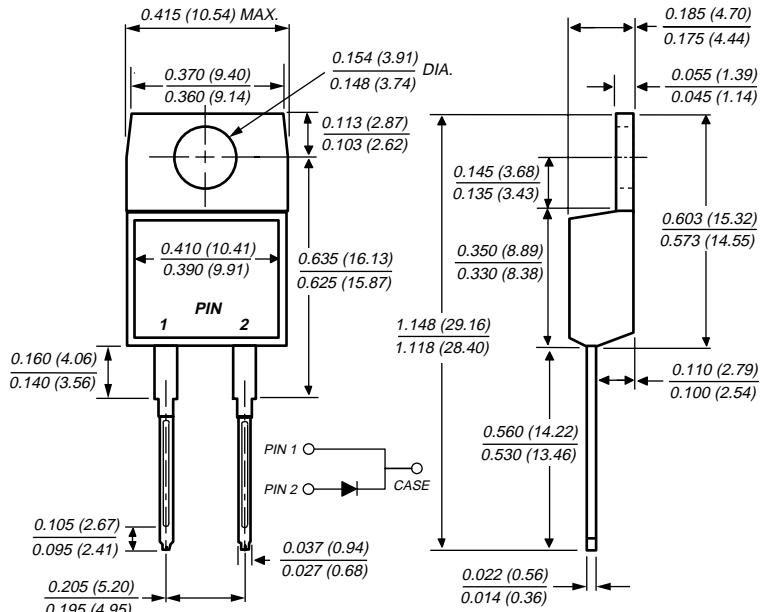




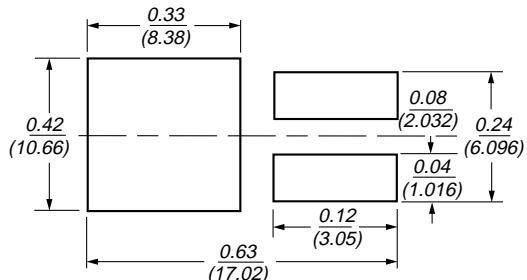
BYW29, BYWF29, BYWB29 Series



TO-220AC (BYW29 Series)



Mounting Pad Layout TO-263AB



Dimensions in inches and (millimeters)

Mechanical Data

Case: JEDEC TO-220AC, ITO-220AC & TO-263AB
molded plastic body

Terminals: Plated leads, solderable per
MIL-STD-750, Method 2026
High temperature soldering in accordance with
CECC 802 / Reflow guaranteed

Polarity: As marked

Mounting Position: Any

Mounting Torque: 10 in. lbs maximum

Weight: approx. 0.05 ounces, 1.35 grams

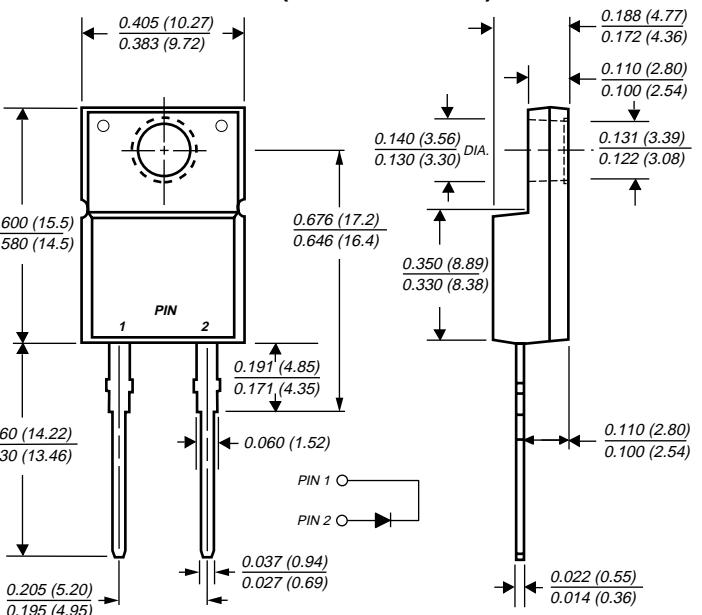
Ultrafast Rectifiers

Reverse Voltage 50 to 200V

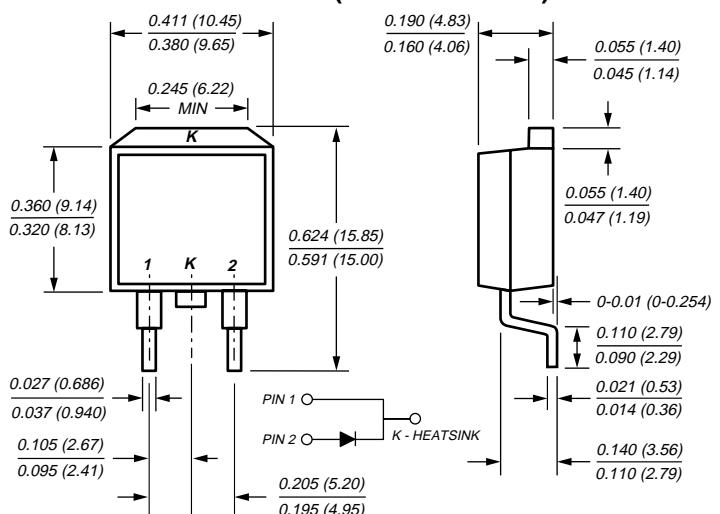
Forward Current 8.0A

Reverse Recovery Time 25ns

ITO-220AC (BYWF29 Series)



TO-263AB (BYWB29 Series)



Features

- Plastic package has Underwriters Laboratory Flammability Classification 94V-0
 - Glass passivated chip junction
 - Low power loss
 - Low leakage current
 - High surge current capability
 - Superfast recovery time for high efficiency

**GENERAL
SEMICONDUCTOR® BYW29, BYWF29, BYWB29 Series**
Ultrafast Rectifiers

Maximum Ratings ($T_C = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	BYW29-50	BYW29-100	BYW29-150	BYW29-200	Unit
Maximum repetitive peak reverse voltage	V_{RRM}	50	100	150	200	V
Maximum RMS voltage	V_{RMS}	35	70	105	140	V
Maximum DC blocking voltage	V_{DC}	50	100	150	200	V
Maximum average forward rectified current at $T_C = 105^\circ\text{C}$	$I_{F(AV)}$	8.0				A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method) per leg	I_{FSM}	100				A
Operating and storage temperature range	T_J, T_{STG}	−65 to +150				°C
RMS Isolation voltage (BYWF type only) from terminals to heatsink with $t = 1.0$ second, $RH \leq 30\%$	V_{ISOL}	4500 ⁽¹⁾ 3500 ⁽²⁾ 1500 ⁽³⁾				V

Electrical Characteristics ($T_C = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	BYW29-50	BYW29-100	BYW29-150	BYW29-200	Unit
Maximum instantaneous forward voltage at: ⁽⁴⁾ $I_F = 20\text{A}, T_J = 25^\circ\text{C}$ $I_F = 8.0\text{A}, T_J = 150^\circ\text{C}$	V_F	1.3 0.8				V
Maximum DC reverse current at rated DC blocking voltage $T_C=25^\circ\text{C}$ $T_C=100^\circ\text{C}$	I_R	10 500				μA
Maximum reverse recovery time at $I_F = 1\text{A}$, $V_R = 30\text{V}$, $dI/dt = 100\text{A}/\mu\text{s}$, $I_{rr} = 10\% I_{RM}$	t_{rr}	25				ns
Typical junction capacitance at 4V, 1MHz	C_J	45				pF

Thermal Characteristics ($T_C = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	BYW	BYWF	BYWB	Unit
Typical thermal resistance from junction to case per leg	$R_{\theta JC}$	TBD	TBD	TBD	°C/W

Notes:

- (1) Clip mounting (on case), where lead does not overlap heatsink with 0.110" offset
- (2) Clip mounting (on case), where leads do overlap heatsink
- (3) Screw mounting with 4-40 screw, where washer diameter is $\leq 4.9\text{mm}$ (0.19")
- (4) Pulse test: 300μs pulse width, 1% duty cycle

**GENERAL
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Ultrafast Rectifiers

Ratings and Characteristic Curves

($T_A = 25^\circ\text{C}$ unless otherwise noted)

Fig. 1 – Maximum Forward Current Derating Curve

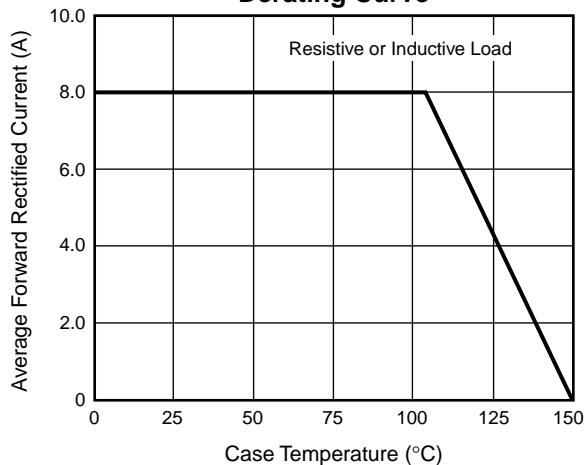


Fig. 2 – Maximum Non-Repetitive Peak Forward Surge Current

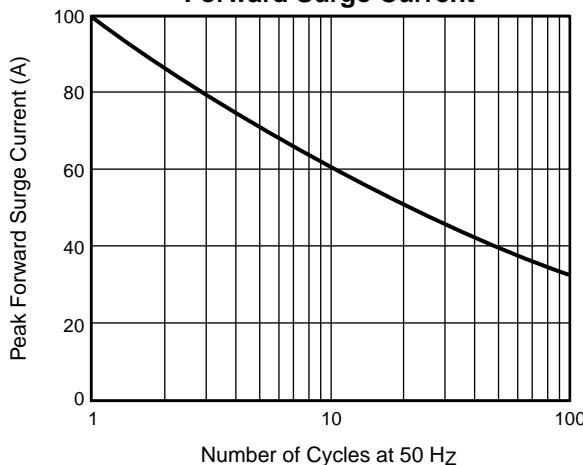


Fig. 3 – Typical Instantaneous Forward Characteristics

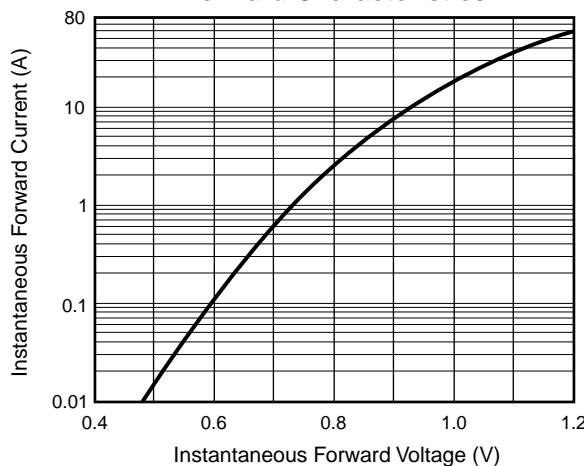


Fig. 4 – Typical Reverse Leakage Characteristics

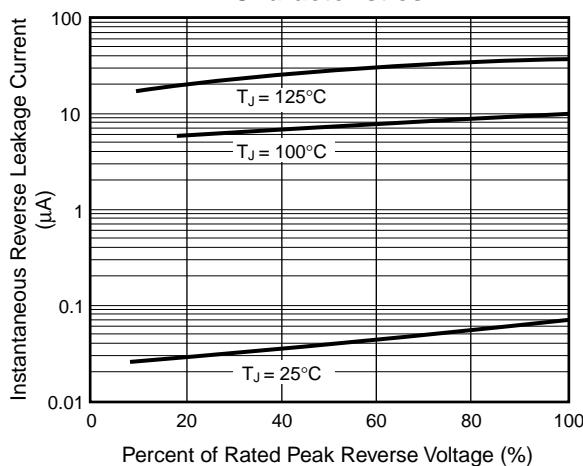


Fig. 5 – Typical Junction Capacitance

